

# Towards Cryogenic Surface Ion Traps

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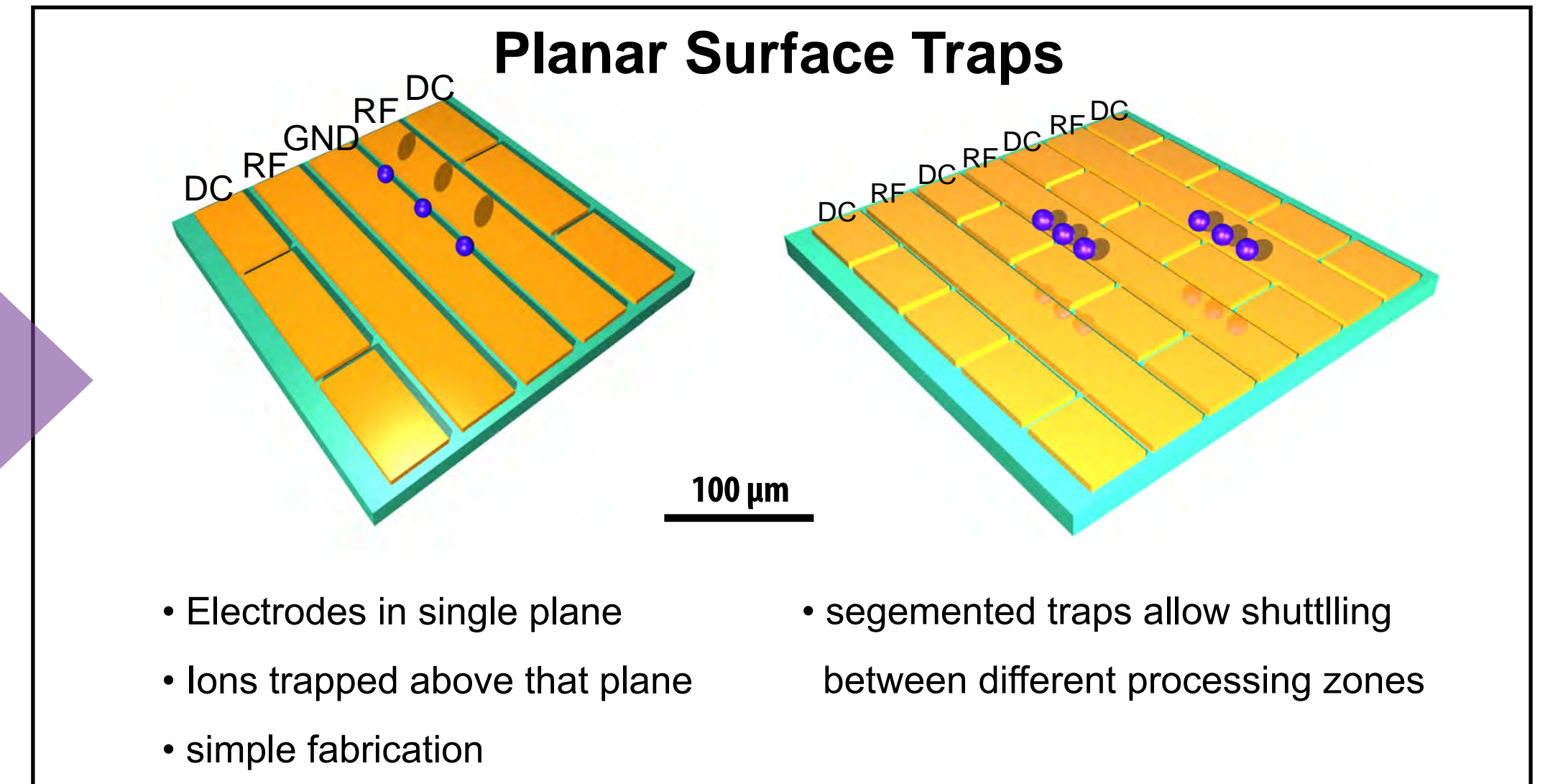
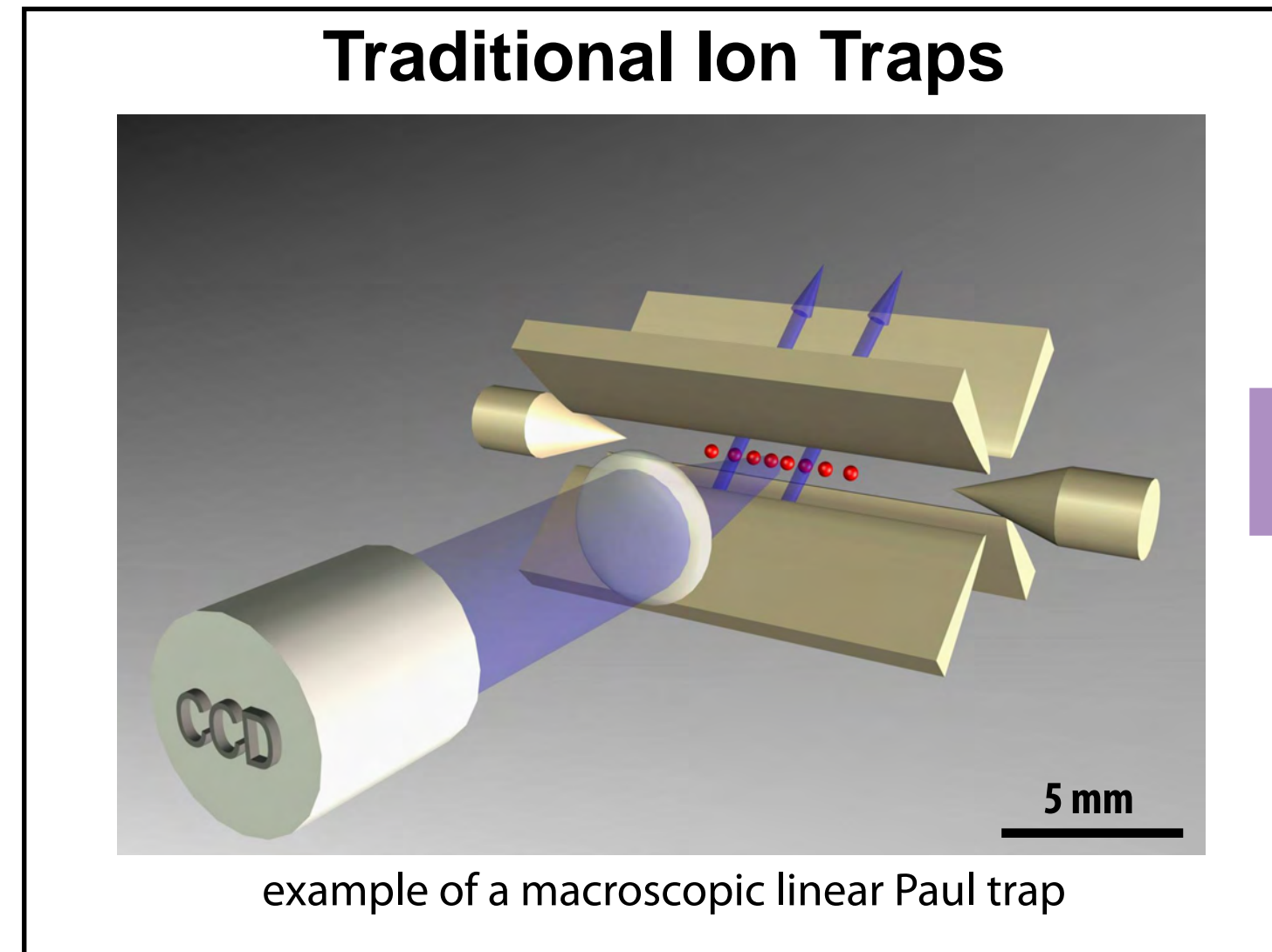
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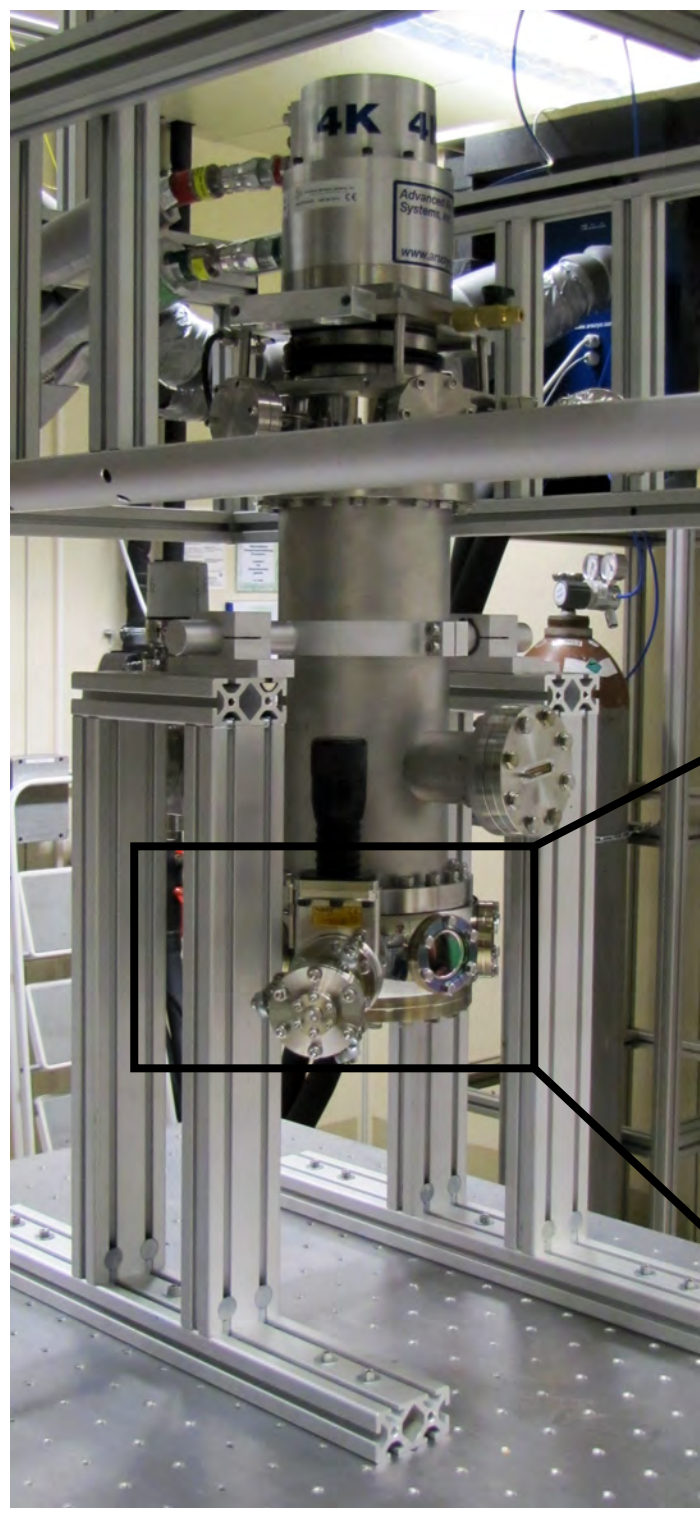
## Motivation

Scalability to many ions remains one of the most significant challenges for ion trap quantum computing.

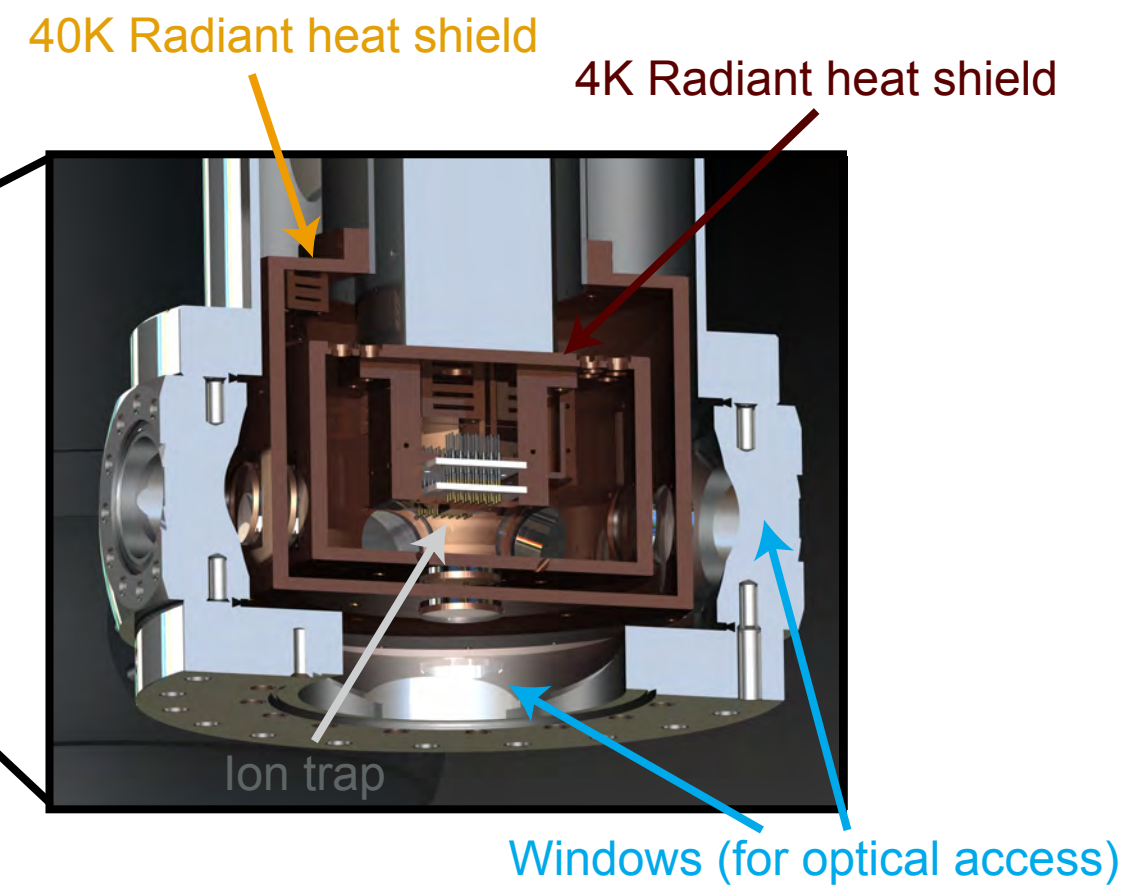
## Micro Ion Traps



## Cryogenic System: Gifford McMahon Cooler



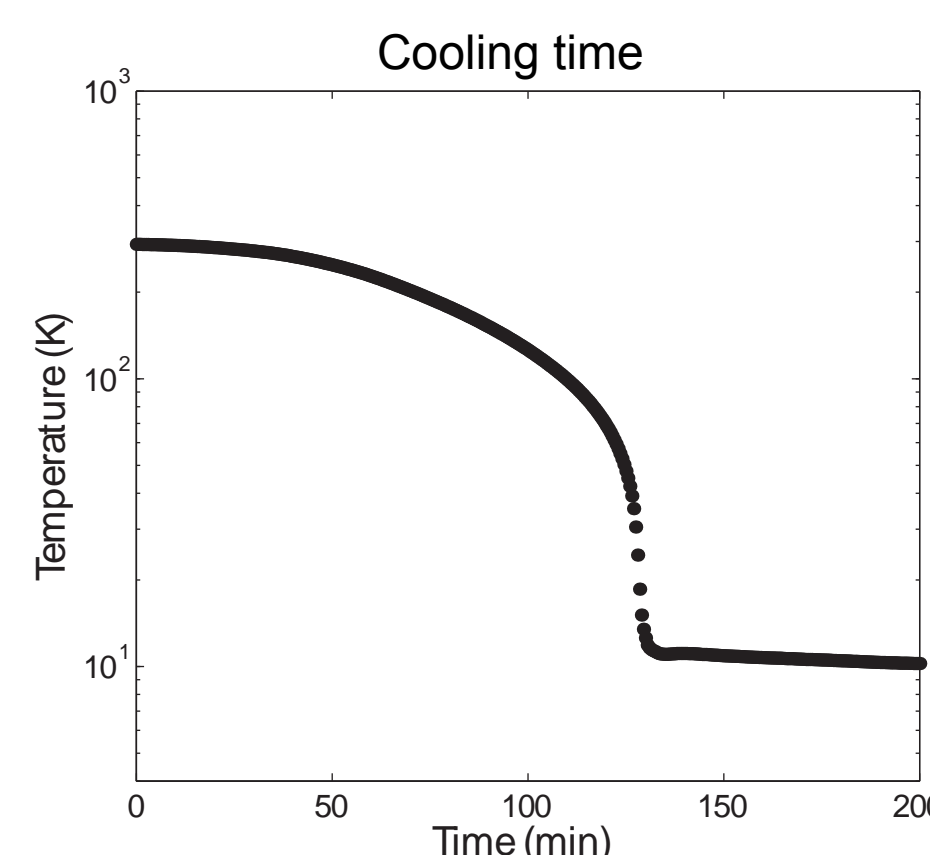
Ion-heating rate can be reduced by ~2 orders of magnitude by cooling trap from 300 K to 6 K<sup>1</sup>



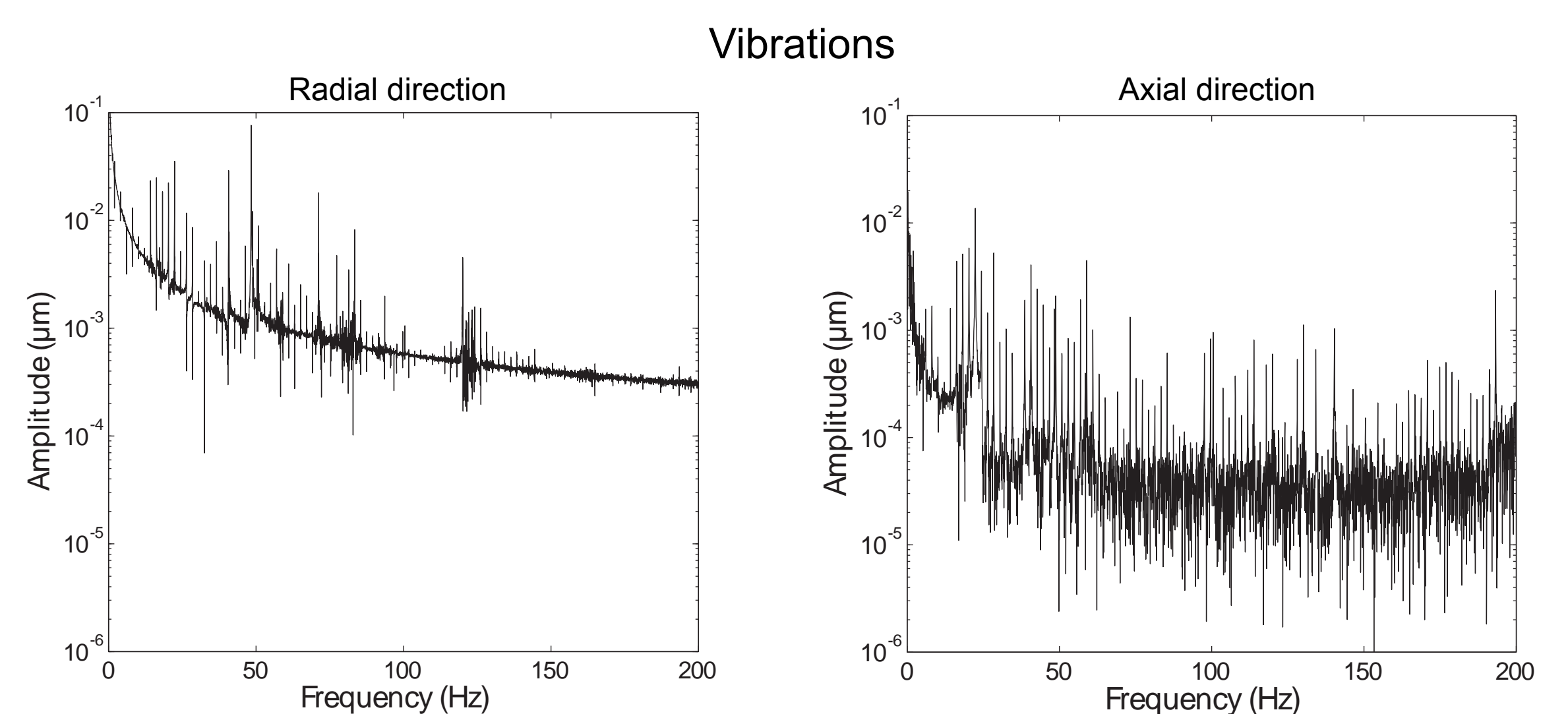
<sup>1</sup>J. Labaziewicz et al., Phys. Rev.Lett. **101**,180602 (2008)

### Setup

- Sample temperature ~6-10 K
- Easily implemented UHV conditions
- Good optical access
- Fast trap-testing turn-around times (few days)

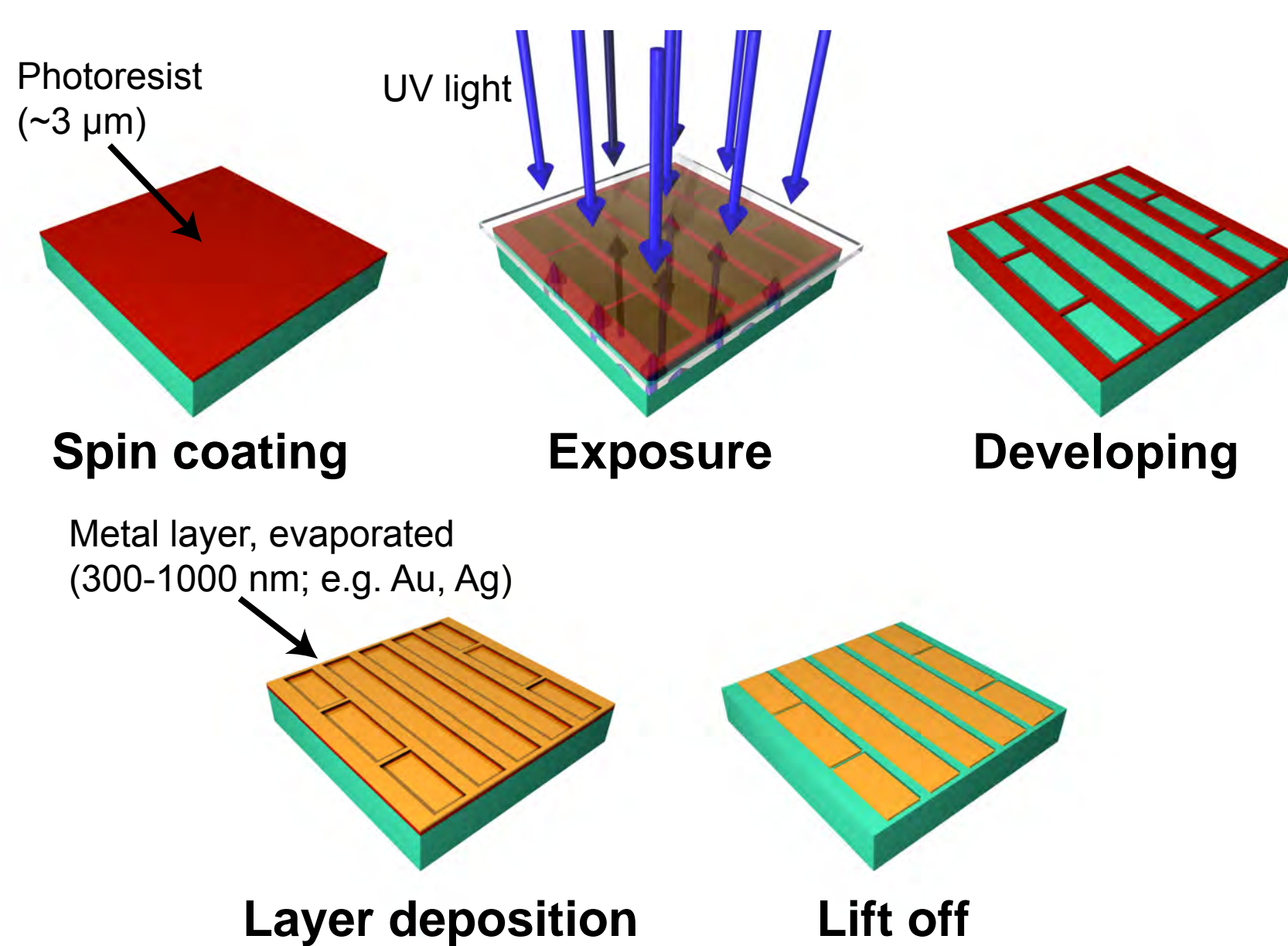


- Low vibrations: vibration isolation interface no mechanical coupling between cryocooler and vacuum chamber



## Trap Fabrication by Photolithography

### Lift-Off Process

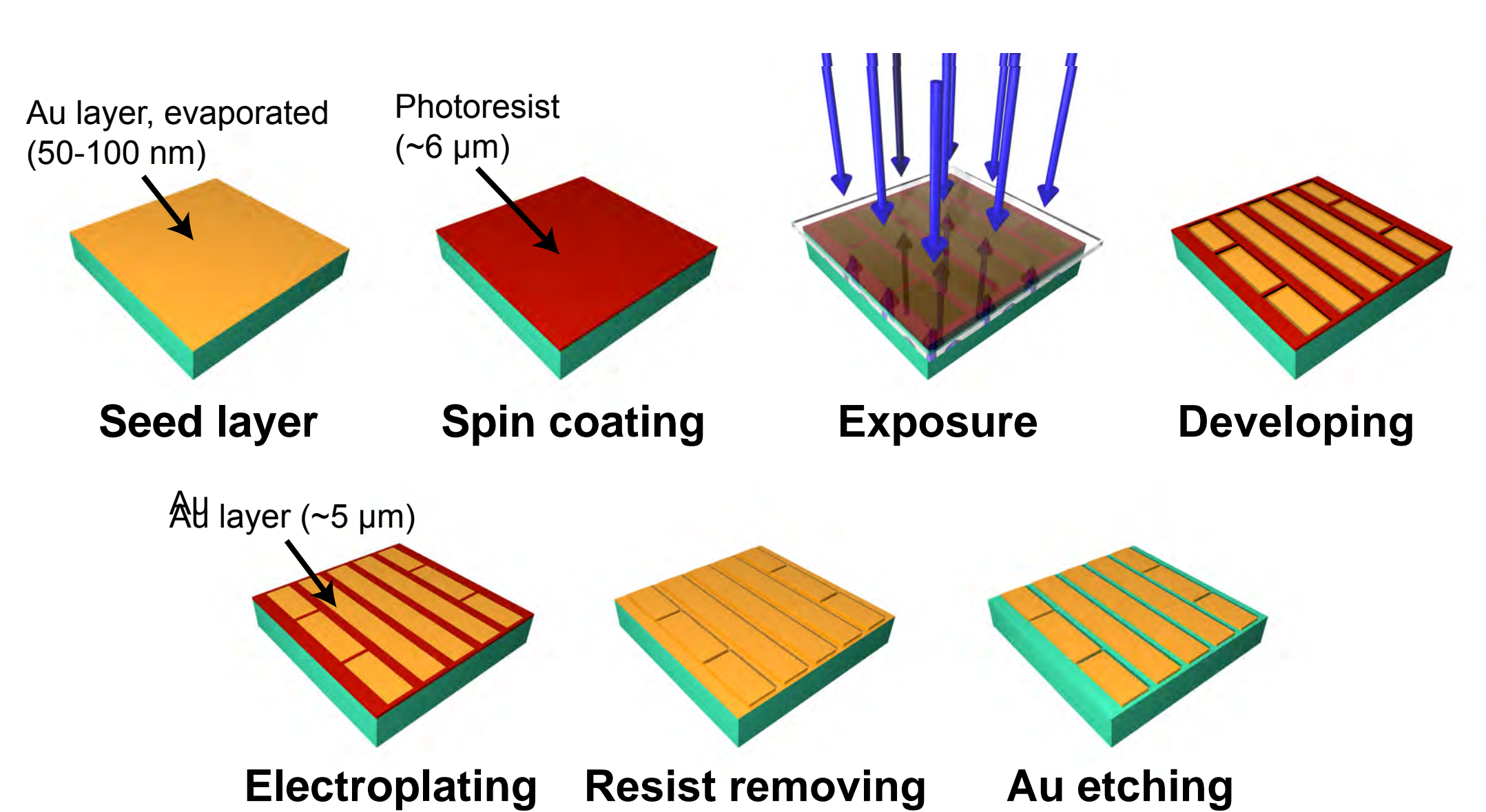


### Lift-Off vs. Electroplating

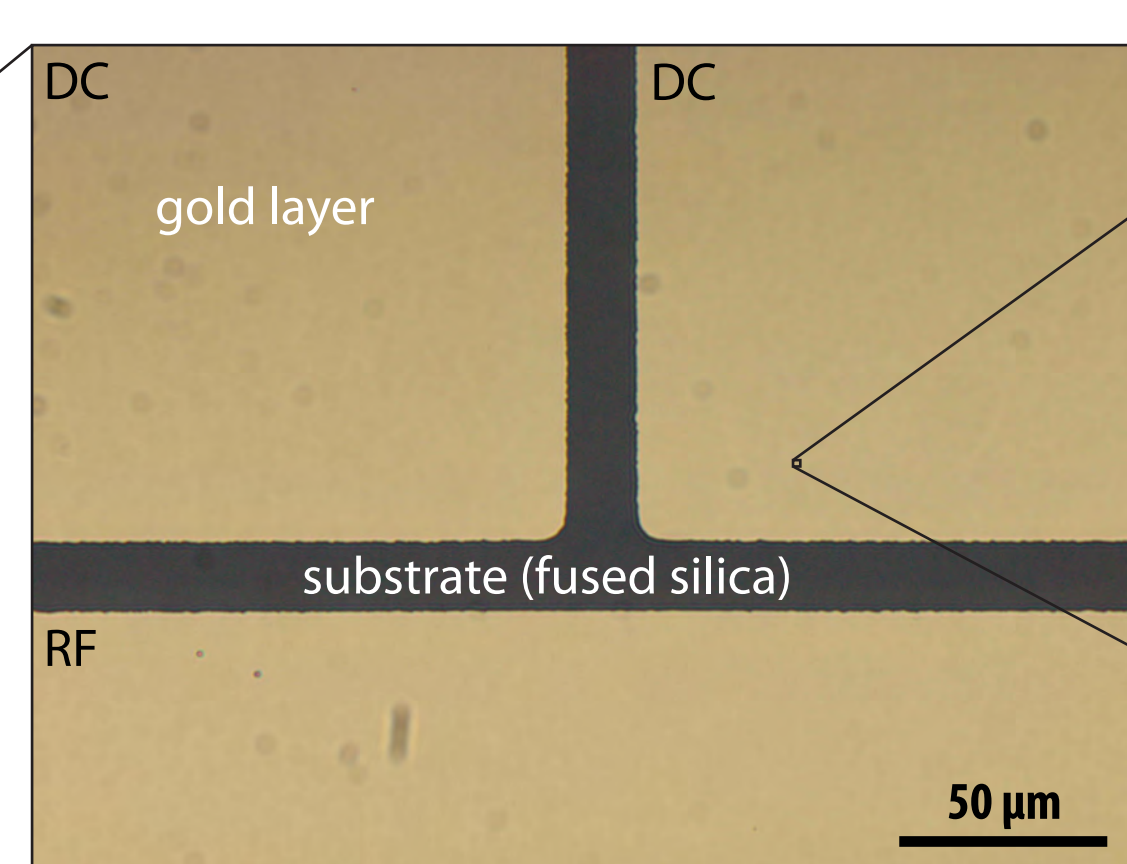
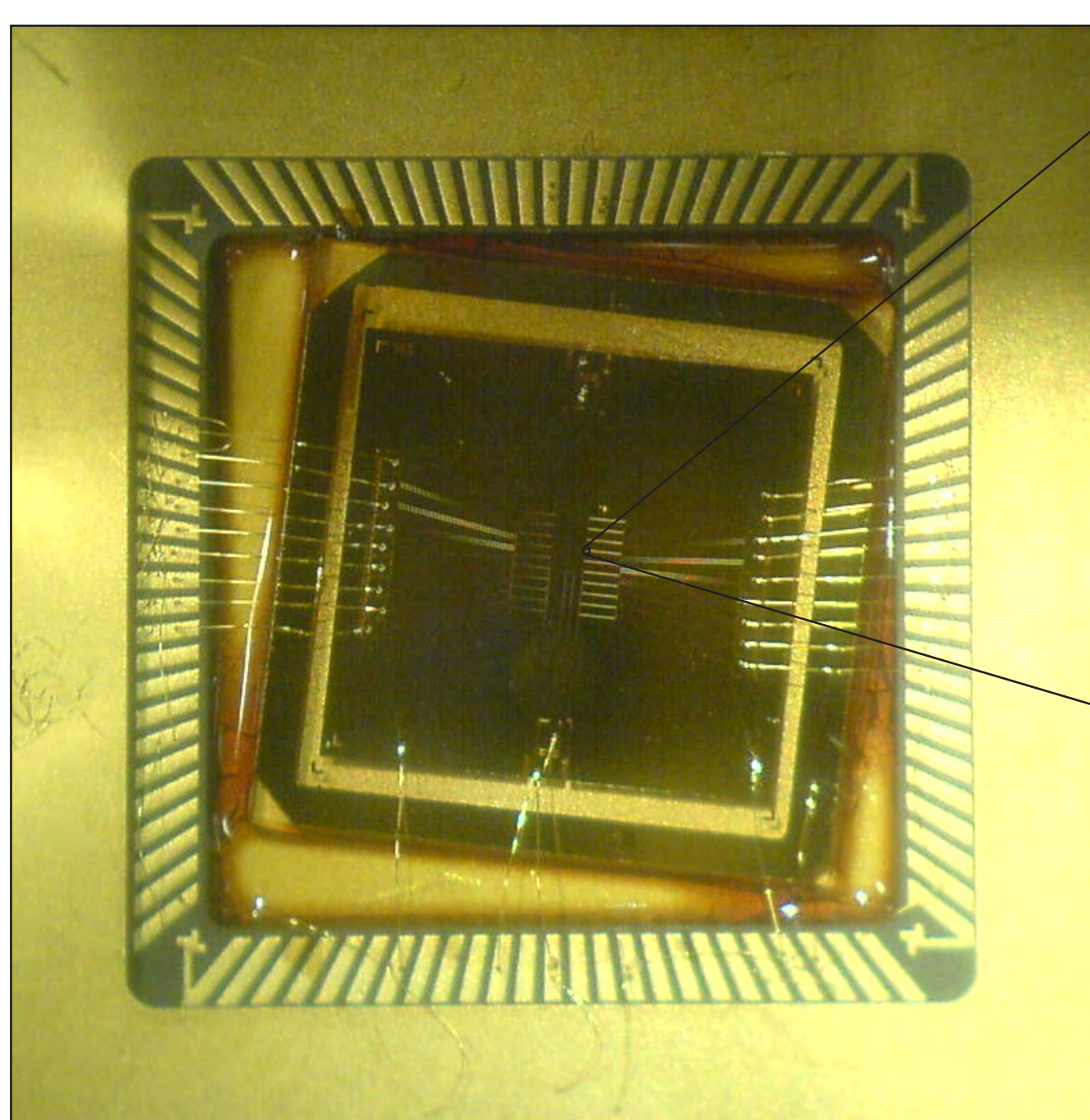
- Lift-Off:
- + Simple process
  - + High resolution (~2 μm)
  - + Low surface roughness (~1 nm)
  - Low electrode thickness (<1000 nm)

- Electroplating:
- + High electrode thickness (>10 μm)
  - + High resolution (~2 μm)
  - + Low surface roughness (~2 nm)
  - Complicated process

### Electroplating Process

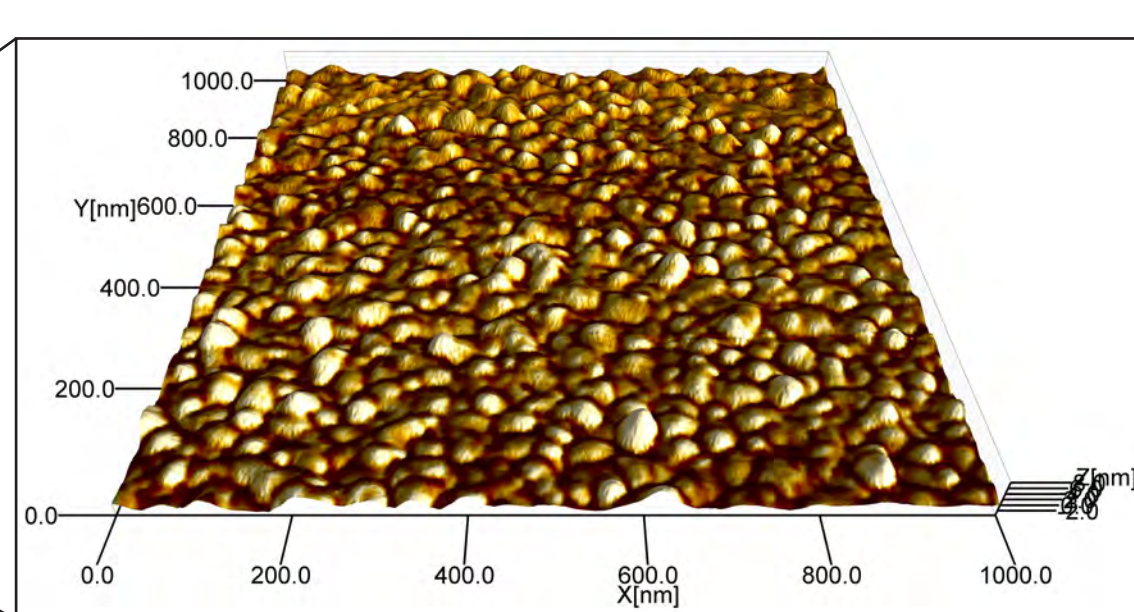


## Our First Home-made Surface Ion Trap (Yedikule, Lift Off)



Light microscope picture

- 9 segments (width: 175 μm)
- Ion-electrode distance: 130 μm
- Gap between electrodes 17 μm
- Gold electrodes (300 nm thick) on fused silica



AFM picture of gold electrodes (surface roughness  $R_q$  1.16 nm)

## Outlook

- Fabricate and optimize new ion traps
- Measure heating rates of different traps at low temperatures (lift off, electroplating)
- Develop 2D arrays
- Implement entangling operations